

Atty. Dkt. No: AMK-11317-1D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of: Paul Robert Hoffman and David Albert Zoba

Application No.: 10/771,072

Art Unit.: 2812

Filing Date: 02/02/2004

Examiner: unknown

For: "STRUCTURES FOR IMPROVING HEAT DISSIPATION IN STACKED SEMICONDUCTOR PACKAGES"

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Date: May 4, 2004

SECOND PRELIMINARY AMENDMENT TRANSMITTAL

1. Transmitted herewith is an amendment for this application.
2. **STATUS:** Applicant is other than a small entity.
3. **EXTENSION OF TERM:** The proceedings herein are for a patent application and the provisions of 37 C.F.R. 1.136 apply. Applicant believes that no extension of term is required. However, this conditional petition is being made to provide for the possibility that applicant has inadvertently overlooked the need for a petition for extension of time.
4. **FEE FOR CLAIMS:** The fee for claims (37 C.F.R. 1.16(b)-(d)) has been calculated as shown below:

	(Col.1)		(Col. 2)	(Col. 3)	LARGE ENTITY	
	Claims Remaining After Amendment		Highest No. Previously Paid For	Present Extra	Rate	Addit. Fee
Total	24	Minus	25	= 0	x \$18 =	\$0
Indep.	4	Minus	4	= 0	x \$86 =	\$0
First Presentation of Multiple Dependent Claim					+ \$290 =	\$0
Total					Addit. Fee	\$0

No additional fee for claims is required.

5. **FEE DEFICIENCY:** If any additional extension and/or fee is required, please charge Deposit Account No. 50-0574.

Customer No. 022888

Tel.: (408) 451-5906


SIGNATURE OF PRACTITIONER

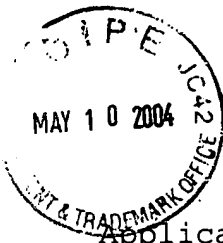
James E. Parsons

Reg. No. 34,691

I hereby certify that this correspondence is being deposited with the United States Postal Service as FIRST CLASS MAIL in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 4, 2004.

Date 5/4/2004

Signature: Rebecca A. Baumann
Rebecca A. Baumann



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Paul Robert Hoffman and David Albert Zoba

Assignee: Amkor Technology, Inc.

Title: Structures For Improving Heat Dissipation In
Stacked Semiconductor Packages

Serial No.: 10/771,072 File Date: 02/02/2004

Examiner: Not Yet Assigned Art Unit: 2812

Docket No.: AMK-11317-1D

Date: May 4, 2004

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SECOND PRELIMINARY AMENDMENT

Dear Sir:

Please amend the application as follows.